

Electronic Version v18
Stylesheet Version v18.0

Title of Invention

BOILING TEMPERATURE DESIGN IN PUMPED MICROCHANNEL COOLING LOOPS

. ( ) 1 May 1

**Application Number:** 

10/643638

Confirmation Number:

4432

First Named Applicant:

Peng Zhou

Attorney Docket Number:

Search string:

( 6068752 or 6090251 or 6096656 or 6100541 or 6101715 or 6119729 or 6126723 or 6129145 or 6129260 or 6131650 or 6146103 or 6154363 or 6159353 or 6171067 or 6174675 or 6176962 or 6186660 or 6210986 or 6216343 or 6221226 or 6227809 or 6234240 or 6238538 or 6277257 or 6287440 or 6301109 or 6313992 or 6317326 or 6321791 or 6322753 or 6324058 or 6351384 or 6337794 or 6388317 or 6396706 or 6400012 or 6406605 or 6415860 or 6416642 or 6417060 or 6424531 or 6443222 or 6444461 or 6457515 or 6495015 or 6537437 or 6543521 or 6553253

### **US Patent Documents**

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

or 6572749 or 6588498 ).pn.

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
MJE	· 1	6068752	2000-05-30	Dubrow et al.			
	2	6090251	2000-07-18	Sundberg et al.			
	3	6096656	2000-08-01	Matzke et al.			
	4	6100541	2000-08-08	Nagle et al.	] ] ]		
	5	6101715	2000-08-15	Fuesser et al.			
	6	6119729	2000-09-19	Oberholzer et al.			
	7	6126723	2000-10-03	Drost et al.			
	8	6129145	2000-10-10	Yamamoto et al.			
	9	6129260	2000-10-10	Andrus et al.			
V	10	6131650	2000-10-17	North et al.			

mJE	11	6146103	2000-11-14	Lee et al.	
$\prod$	12	6154363	2000-11-28	Chang	
	13	6159353	2000-12-12	West et al.	
	14	6171067	2001-01-09	Parce	B1
	15	6174675	2001-01-16	Chow et al.	B1
	16	6176962	2001-01-23	Soane et al.	B1
	17	6186660	2001-02-13	Kopf-Sill et al.	B1
	18	6210986	2001-04-03	Arnold et al.	B1
	19	6216343	2001-04-17	Leland et al.	B1
	20	6221226	2001-04-24	Kopf-Sill	B1
	21	6227809	2001-05-08	Forster et al.	B1
	22	6234240	2001-05-22	Cheon	B1
	23	6238538	2001-05-29	Parce et al.	B1
	24	6277257	2001-08-21	Paul et al.	B1
	25	6287440	2001-09-11	Arnold et al.	B1
	26	6301109	2001-10-09	Chu et al.	B1
	27	6313992	2001-11-06	Hildebrandt	B1
	28	6317326	2001-11-13	Vogel et al.	B1
	29	6321791	2001-11-27	Chow	B1
	30	6322753	2001-11-27	Lindberg et al.	B1
	31	6324058	2001-11-27	Hsiao	B1
$\Box$	32	6351384	2002-02-26	Daikoku et al.	B1
$\prod$	33	6337794	2002-01-08	Agonafer et al.	B1
	34	6388317	2002-05-14	Reese	<b>B</b> 1.
$\prod$	35	6396706	2002-05-28	Wohlfarth	B1
$\Box$	36	6400012	2002-06-04	Miller et al.	B1
$\prod$	37	6406605	2002-06-18	Moles	B1
	38	6415860	2002-07-09	Kelly et al.	B1
	39	6416642	2002-07-09	Alajoki et al.	B1
$\prod$	40	6417060	2002-07-09	Tavkhelidze et al.	B1
	41	6424531	2002-07-23	Bhatti et al.	B1
	42	6443222	2002-09-03	Yun et al.	B1
	43	6444461	2002-09-03	Knapp et al.	B1
	44	6457515	2002-10-01	Vafai et al.	B1
	45	6495015	2002-12-17	Schoeniger et al.	B1
.4	46	6537437	2003-03-25	Galambos et al.	B1

MJE	47	6543521	2003-04-08	Sato et al.	В1
	48	6553253	2003-04-22	Chang	B1
	49	6572749	2003-06-03	Paul et al.	B1
	50	6588498	2003-07-08	Reysin et al.	B1

Examiner Name	Date
n/J.3/	1/5/06

# APR 2 9 2004

### **ELECTRONIC INFORMATION DISCLOSURE STATEMENT**

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( 6591625 or 6632655 or 20010016985 or

20010024820 or 20010044155 or 20010045270

or 20010046703 or 20010055714 or 20020011330 or 20020134543 ).pn.

### **US Patent Documents**

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
NJE	1	6591625	2003-07-15	Simon	B1		
	2	6632655	2003-10-14	Mehta et al.	B1		

# **US Published Applications**

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
UZE	1	20010016985	2003-08-30	Insley et al.	A1		
	2	20010024820	2001-09-27	Mastromatteo et al.	A1		11
	3	20010044155	2001-11-22	Paul et al.	A1		
	4	20010045270	2001-11-29	Bhatti et al.	A1		
	5	20010046703	2001-11-29	Burns et al.	A1		
	6	20010055714	2001-12-27	Cettour-Rose et al.	A1		
	7	20020011330	2002-01-31	Insley et al.	A1		
V	8	20020134543	2002-09-26	Estes et al.	A1		

# Signature

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m /g	1/5/06	



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( 5380956 or 5383340 or 5421943 or 5427174 or 5436793 or 5459099 or 5508234 or 5514832 or 5514906 or 5544696 or 5548605 or 5575929 or 5579828 or 5585069 or 5641400 or 5692558 or 5696405 or 5703536 or 5704416 or 5727618 or 5774779 or 5759014 or 5763951 or 5800690 or 5801442 or 5835345 or 5836750 or 5858188 or 5863708 or 5869004 or 5870823 or 5874795 or 5876655 or 5880017 or 5880524 or 5901037 or 5936192 or 5940270 or 5942093 or 5964092 or 5965001 or 5965813 or 5978220 or 5997713 or 5998240 or 6007309 or 6010316 or 6013164

or 6019882 or 6054034 ).pn.

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Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
MDE	1	5380956	1995-01-10	Loo et al.			
	2	5383340	1995-01-24	Larson et al.			
	3	5421943	1995-06-06	Tam et al.			
	4	5427174	1995-06-27	Lomolino, Sr. et al.			
	5	5436793	1995-07-25	Sanwo et al.			
	6	5459099	1995-10-17	Hsu			
	7	5508234	1996-04-16	Dusablon, Sr. et al.			
	8	5514832	1996-05-07	Dusablon, Sr. et al.			
	9	5514906	1996-05-07	Love et al.			
1	10	5544696	1996-08-13	Leland			

MJE	11	5548605	1996-08-20	Benett et al.
	12	5575929	1996-11-19	Yu et al.
	13	5579828	1996-12-03	Reed et al.
	14	5585069	1996-12-17	Zanzucchi et al.
	15	5641400	1997-06-24	Kaltenbach et al.
	16	5692558	1997-12-02	Hamilton et al.
D[	17	5696405	1997-12-09	Weld
T	18	5703536	1997-12-30	Davis et al.
	19	5704416	1998-01-06	Larson et al.
	20	5727618	1998-03-17	Mundinger et al.
	21	5774779	1998-06-30	Tuchinskiy
	22	5759014	1998-06-02	Van Lintel
	23	5763951	1998-06-09	Hamilton et al.
	24	5800690	1998-09-01	Chow et al.
	25	5801442	1998-09-01	Hamilton et al.
	26	5835345	1998-11-10	Staskus et al.
	27	5836750	1998-11-17	Cabuz
	28	5858188	1999-01-12	Soane et al.
	29	5863708	1999-01-26	Zanzucchi et al.
	30	5869004	1999-02-09	Parce et al.
	31	5870823	1999-02-16	Bezama et al.
	32	5874795	1999-02-23	Sakamoto
	33	5876655	1999-03-02	Fisher
	34	5880017	1999-03-09	Schwiebert et al.
	35	5880524	1999-03-09	Xie
	36	5901037	1999-05-04	Hamilton et al.
	37	5936192	1999-08-10	Tauchi
	38	5940270	1999-08-17	Puckett
	39	5942093	1999-08-24	Rakestraw et al.
	40	5964092	1999-10-12	Tozuka et al.
	41	5965001	1999-10-12	Chow et al.
	42	5965813	1999-10-12	Wan et al.
	43	5978220	1999-11-02	Frey et al.
	44	5997713	1999-12-07	Beetz, Jr. et al.
	45	5998240	1999-12-07	Hamilton et al.
TI	46	6007309	1999-12-28	Hartley

1	MJE	47	6010316	2000-01-04	Haller et al.
		48	6013164	2000-01-11	Paul et al.
١		49	6019882	2000-02-01	Paul et al.
	V	50	6054034	2000-04-25	Soane et al.

Examiner Name	Date
m/s	i/s/06

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( 3654988 or 3817321 or 3823572 or 3923426 or 3929154 or 4109707 or 4194559 or 4248295 or 4312012 or 4450472 or 4485429 or 4516632 or 4540115 or 4561040 or 4567505 or 4573067 or 4664181 or 4758926 or 4866570 or 4868712 or 4894709 or 4896719 or 4908112 or 4938280 or 5009760 or 5016138 or 5057908 or 5058627 or 5070040 or 5083194 or 5088005 or 5096388 or 5099311 or 5099910 or 5125451 or 5131233 or 5203401 or 5218515 or 5219278 or 5230564 or 5232047 or 5239200 or 5263251 or 5274920 or 5281026 or 5308429 or 5309319 or 5317805

or 5325265 or 5336062 ).pn.

### **US Patent Documents**

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init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
WIE	1	3654988	1972-04-11	Clayton, III			
	2	3817321	1974-06-18	von Cube et al.			
	3	3823572	1974-07-16	Cochran, Jr.			
	4	3923426	1975-12-02	Theeuwes			
	5	3929154	1975-12-30	Goodwin			
	6	4109707	1978-08-29	Wilson et al.			
	7	4194559	1980-03-25	Eastman			
	8	4248295	1981-02-03	Ernst et al.			
	9	4312012	1982-01-19	Frieser et al.			
V	10	4450472	1984-05-22	Tuckerman et al.			

MJE	11	4485429	1984-11-27	Mittal
	12	4516632	1985-05-14	Swift et al.
	13	4540115	1985-09-10	Hawrylo
	14	4561040	1985-12-24	Eastman et al.
	15	4567505	1986-01-28	Pease et al.
	16	4573067	1986-02-25	Tuckerman et al.
	17	4664181	1987-05-12	Sumberg
	18	4758926	1988-07-19	Herrell et al.
	19	4866570	1989-09-12	Porter
	20	4868712	1989-09-19	Woodman
$\Box$	21	4894709	1990-01-16	Phillips et al.
	22	4896719	1990-01-30	O'Neill et al.
	23	4908112	1990-03-13	Pace
	24	4938280	1990-07-03	Clark
	25	5009760	1991-04-23	Zare et al.
	26	5016138	1991-05-14	Woodman
	27	5057908	1991-10-15	Weber
	28	5058627	1991-10-22	Brannen
	29	5070040	1991-12-03	Pankove
$\prod$	30	5083194	1992-01-21	Bartilson
	31	5088005	1992-02-11	Ciaccio
	32	5096388	1992-03-17	Weinberg
	33	5099311	1992-03-24	Bonde et al.
	34	5099910	1992-03-31	Walpole et al.
	35	5125451	1992-01-30	Matthews
	36	5131233	1992-07-21	Cray et al.
	37	5203401	1993-04-20	Hamburgen et al.
	38	5218515	1993-06-08	Bernhardt
	. 39	5219278	1993-06-15	Van Lintel
	40	5230564	1993-07-27	Bartilson et al.
	41	5232047	1993-08-03	Matthews
	42	5239200	1993-08-24	Messina et al.
	43	5263251	1993-11-23	Matthews
	44	5274920	1994-01-04	Mathews
	45	5281026	1993-07-27	Bartilson et al.
V	46	5308429	1994-05-03	Bradley

	NJE	47	5309319	09319 1994-05-03 Messina	
		48	5317805	1994-06-07	Hoopman et al.
		49	5325265	1994-06-28	Turlik et al.
P	T	50	5336062	1994-08-09	Richter

Examiner Name	Date
m' p 'y	1/5/06

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4432

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Art Unit:

Examiner:

Search string:

( 6438984 or 6581388 or 6587343 ).pn

<u>Certification:</u> This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:

That no item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the person signing the certification after making reasonable inquiry, no item of information contained in the information disclosure statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the information disclosure statement.

#### **US Patent Documents**

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
MJE	1	6438984	2002-08-27	Novotny et al.	B1		
	2	6581388	2003-06-24	Novotny et al.	B2		
<b>1</b>	3	6587343	2003-07-01	Novotny et al.	B2		

Examiner Name	Date
m 2.5	1/5/06

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( 2039593 or 4574876 or 6206022 or 6253835 or 6437981 ).pn

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in	iit	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
m	J E	1	2039593	1936-05-05	T. N. Hubbuch et al.			
П		2	4574876	1986-03-11	Aid			
		3	6206022	2001-03-27	Tsai et al.	B1		
		4	6253835	2001-07-03	Chu et al.	B1		
		5	6437981	2002-08-20	Newton et al.	B1		

Examiner Name	Date
m 2 g	1/5/06